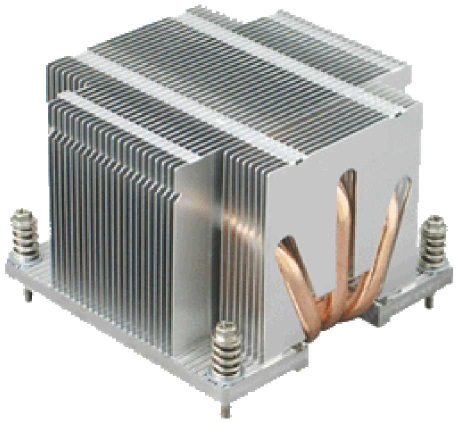
HEL-00019-N1-GP



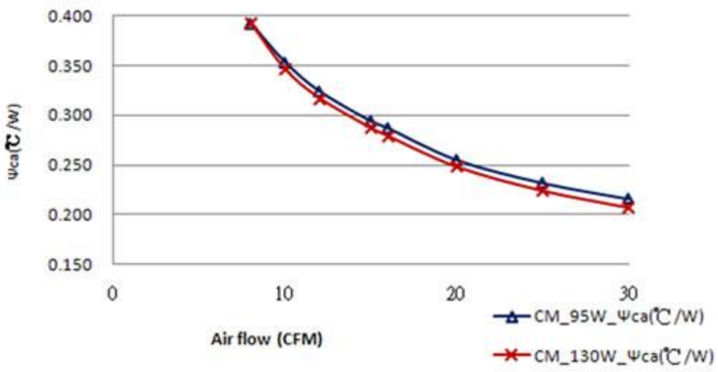
Thermal and Mechanical Spec

Thermal performance for 95W/130W CPU

HSK Assembly Weight: 339 g

CPU Loading: 65 lbf

Performance Curve



Application

LGA 1366/1356 (Socket B/B2) M3

Test result:

	95W	130W
Flow (CFM)	Rca (℃/W)	Rca (℃/W)
8	0.3091	0.3271
10	0.2892	0.2867
12	0.2617	0.2636
15	0.237	0.2368
16	0.2344	0.2325
20	0.2133	0.2114
25	0.1979	0.1952
30	0.188	0.1855

Component Specifications

Application System	2U Form Factor Passive Solution
Material	Aluminum Fin + Aluminum Base + Heat pipe Diameter 6 × 3
Dimension	88.9L × 88.9W × 63H mm
Fin	Thick=0.3mm, Pitch=2.3mm, 68 fin (Solder Free)
Thermal interface Material	Shin Etsu 7783 (35 × 35 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.

Safety